



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-06-13
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

While STMicroelectronics has endeavored to provide information which is accurate and up to date, this document and its contents are provided on a strict 'as is' and 'as available' basis. STMicroelectronics disclaims all warranties, express or implied related to this document and its contents, including but not limited to implied warranties of completeness, truth, accuracy, merchantability, fitness for a particular purpose and non-infringement. ST shall have no responsibility and assumes no liability for any cost, loss or damage of any kind which could arise, directly or indirectly, from the use or inability to use this document and/or its contents.


Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
------------------------------	------	----------------------------	----------

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L99H01QFTR	A55V*UH49AE6	A	MU1A	2016-06-13
Amount		UoM	Unit type	ST ECOPACK Grade
180.00		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nicke/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	1.4x7x7	32	flat	
Comment	Package: 5V LQFP 32 7x7x1.4 1			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7a' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2015				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	ASSV*UH49AE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	9.594	mg	supplier	die	Silicon (Si)	7440-21-3		9.174	mg	956223	50967
				supplier	metallization	Aluminium (Al)	7429-90-5		0.078	mg	8130	433
				supplier	metallization	Copper (Cu)	7440-50-8		0.078	mg	8130	433
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	834	44
				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.015	mg	1563	83
				supplier	passivation	Indium Tin oxide (In2O3:SnO2)	50926-11-9		0.169	mg	17615	939
				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.005	mg	522	28
				supplier	back side metallization	Gold (Au)	7440-57-5		0.014	mg	1459	78
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.047	mg	4899	261
				supplier	polymer die coating	Polymer resist (Black resist)	Proprietary		0.006	mg	625	33
Leadframe	Copper & its alloys	62.815	mg	supplier	alloy	Copper (Cu)	7440-50-8		59.778	mg	951652	332100
				supplier	alloy	Nickel (Ni)	7440-02-0		1.864	mg	29674	10356
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.093	mg	1481	518
				supplier	alloy	Silicon (Si)	7440-21-3		0.404	mg	6432	2244
				supplier	metallization	Nickel (Ni)	7440-02-0		0.619	mg	9854	3439
				supplier	metallization	Palladium (Pd)	7440-05-3		0.040	mg	637	222
				supplier	metallization	Gold (Au)	7440-57-5		0.017	mg	270	94
Die attach	Other inorganic materials	2.408	mg	supplier	glue or tape	Bismaleimide resin	35325-39-4		0.072	mg	29900	400
				supplier	glue or tape	isobornyl Methacrylate	7534-94-3		0.181	mg	75166	1006
				supplier	glue or tape	Silver (Ag)	7440-22-4		2.155	mg	894934	11972
Bonding wire	Precious metals	0.614	mg	supplier	wire	Gold (Au)	7440-57-5		0.607	mg	988599	3372
				supplier	wire	Copper (Cu)	7440-50-8		0.004	mg	6515	22
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	3257	11
				supplier	wire	Platinum (Pt)	7440-06-4		0.001	mg	1629	6
Encapsulation	Other inorganic materials	104.569	mg	supplier	mold compound	Epoxy Resin	85954-11-6		8.365	mg	79995	46472
				supplier	mold compound	Phenol Resin	26834-02-6		4.183	mg	40002	23239
				supplier	mold compound	Silica, vitreous	60676-86-0		91.080	mg	871004	506000
				supplier	mold compound	Carbon black	1333-86-4		0.523	mg	5002	2906
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.418	mg	3997	2322